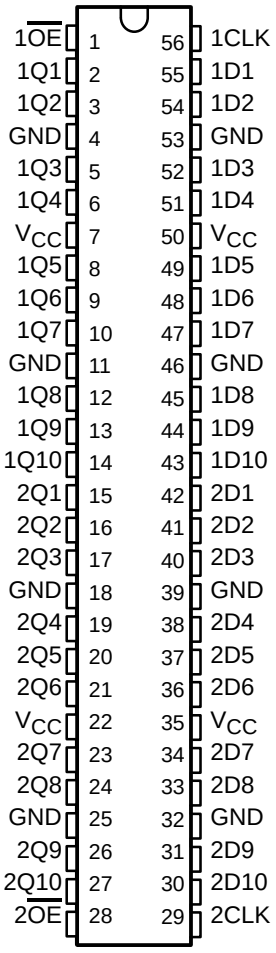
- **Members of the Texas Instruments Widebus™ Family**
- **Packaged in Shrink Small-Outline 300-mil Packages (DL) and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings**
- **Provides Extra Data Width Necessary for Wider Address/Data Paths or Buses with Parity**
- **Flow-Through Architecture to Optimize Printed-Circuit-Board (PCB) Layout**
- **Distributed V_{CC} and GND Pin Configuration to Minimize High-Speed Switching Noise**
- **EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process**
- **500-mA Typical Latch-Up Immunity at 125°C**

l6821...WD PACKAGE
l6821...DL PACKAGE

(TOP VIEW)



description

These 20-bit flip-flops feature three-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

These devices can be used as two 10-bit flip-flops or one 20-bit flip-flop.

On the positive transition of the clock the Q outputs will follow the D inputs. A buffered output enable ($\overline{OE}$) input can be used to place the twenty outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state the outputs neither load nor drive the bus lines significantly. The output enable ($\overline{OE}$) does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74AC16821 is packaged in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The 54AC16821 is characterized over the full military temperature range of –55°C to 125°C. The 74AC16821 is characterized for operation from –40°C to 85°C.

PRODUCT PREVIEW

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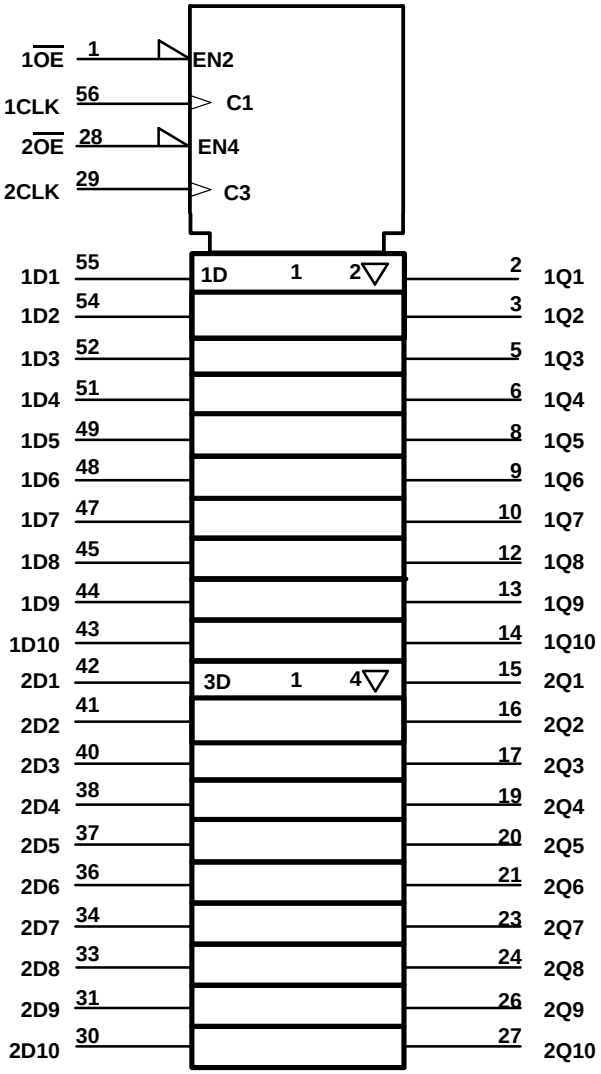
FUNCTION TABLE

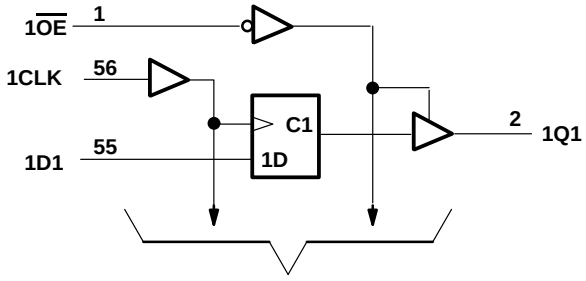
INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

logic symbol †

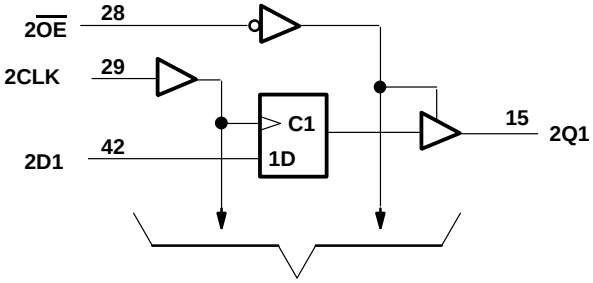


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To 9 Other Channels



To 9 Other Channels

PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ± 20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ± 50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ± 50 mA
Continuous current through V_{CC} or GND pins . . . . . ± 500 mA
Maximum package power dissipation at T_A = 55°C (in still air) . . . . . 1 W
Storage temperature range . . . . . −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

			54AC16821			74AC16821			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		3	5	5.5	3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			2.1			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 5.5 V	3.85			3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9			0.9	V
		V_{CC} = 4.5 V			1.35			1.35	
		V_{CC} = 5.5 V			1.65			1.65	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			−4			−4	mA
		V_{CC} = 4.5 V			−24			−24	
		V_{CC} = 5.5 V			−24			−24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12			12	mA
		V_{CC} = 4.5 V			24			24	
		V_{CC} = 5.5 V			24			24	
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	0		10	ns/V
T_A	Operating free-air temperature		−55		125	−40		85	°C

NOTE 2: Unused or floating (input or I/O) must be held high or low

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			54AC16821		74AC16821		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}		I_{OH} = –50 µA	3 V	2.9			2.9		2.9		V
			4.5 V	4.4			4.4		4.4		
			5.5 V	5.4			5.4		5.4		
		I_{OH} = –4 mA	3 V	2.58			2.4		2.48		
		I_{OH} = –24 mA	4.5 V	3.94			3.7		3.8		
			5.5 V	4.94			4.7		4.8		
		I_{OH} = –50 mA†	5.5 V				3.85				
		I_{OH} = –75 mA†	5.5 V						3.85		
V_{OL}		I_{OL} = 50 µA	3 V			0.1		0.1		0.1	V
			4.5 V			0.1		0.1		0.1	
			5.5 V			0.1		0.1		0.1	
		I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
		I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
			5.5 V			0.36		0.5		0.44	
		I_{OL} = 50 mA†	5.5 V					1.65			
		I_{OL} = 75 mA†	5.5 V							1.65	
I_I	Control inputs	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	µA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			8		160		80	µA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4.5						pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16						pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V

		T_A = 25°C		54AC16821		74AC16821		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency							MHz
t_w	Pulse duration, CLK high or low							ns
t_{su}	Setup time, data before CLK↑							ns
t_h	Hold time, data after CLK↑							ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V

		T_A = 25°C		54AC16821		74AC16821		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency							MHz
t_w	Pulse duration, CLK high or low							ns
t_{su}	Setup time, data before CLK↑							ns
t_h	Hold time, data after CLK↑							ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16821		74AC16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}										MHz
t_{PLH}	CLK	Any Q								ns
t_{PHL}										
t_{PZH}	$\overline{OE}$	Any Q								ns
t_{PZL}										
t_{PHZ}	$\overline{OE}$	Any Q								ns
t_{PLZ}										

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

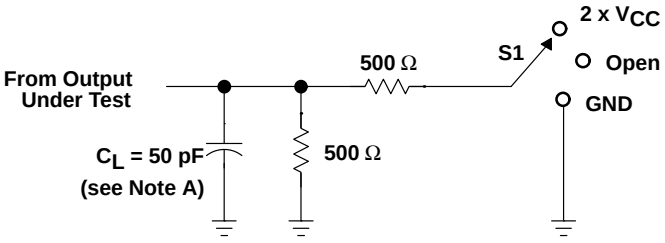
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			54AC16821		74AC16821		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}										MHz
t_{PLH}	CLK	Any Q								ns
t_{PHL}										
t_{PZH}	$\overline{OE}$	Any Q								ns
t_{PZL}										
t_{PHZ}	$\overline{OE}$	Any Q								ns
t_{PLZ}										

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per flip-flop	Outputs enabled	C_L = 50 pF, f = 1 MHz		pF
		Outputs disabled			

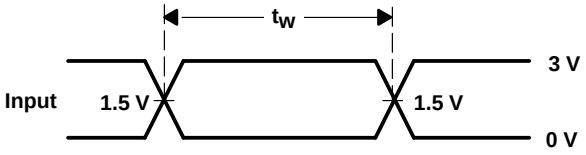
PRODUCT PREVIEW

PARAMETER MEASUREMENT INFORMATION

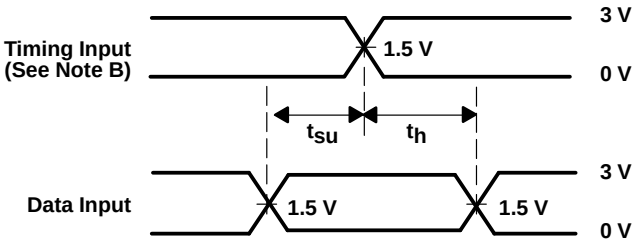


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 x V_{CC}
t_{PHZ}/t_{PZH}	GND

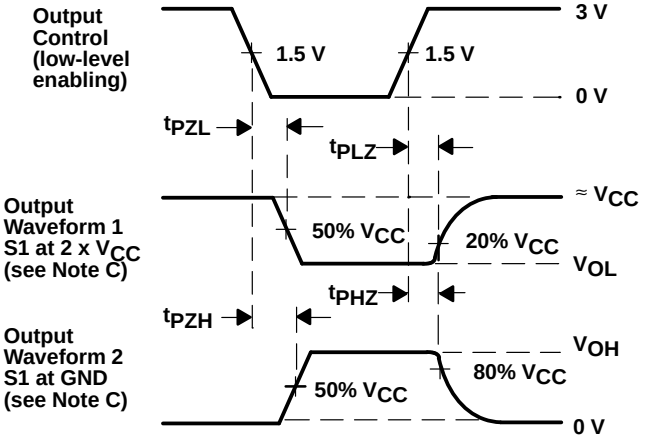
LOAD CIRCUIT FOR OUTPUTS



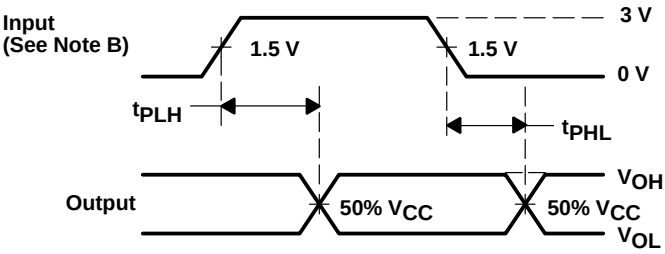
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns. For testing pulse duration: $t_r = t_f$ = 1 to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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